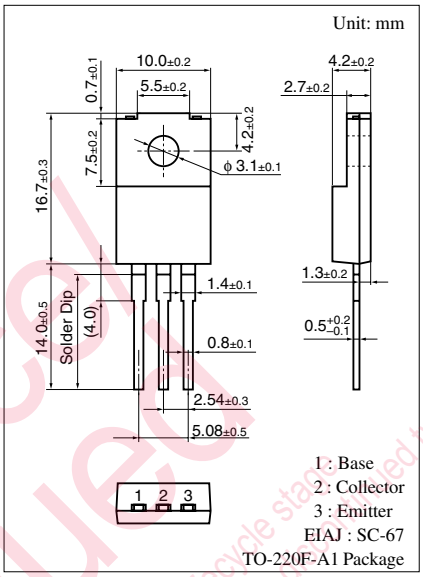
2SC4533

Silicon NPN triple diffusion planar type

For high breakdown voltage high-speed switching



■ Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

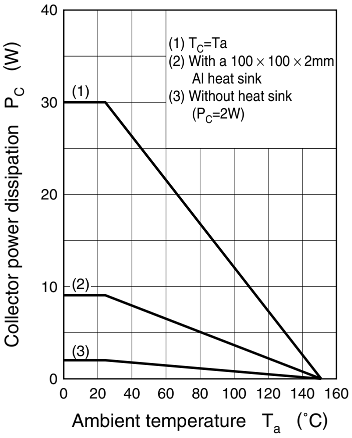
■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Collector to base voltage		V_{CBO}	500	V
Collector to emitter voltage		V_{CES}	500	V
		V_{CEO}	400	V
Emitter to base voltage		V_{EBO}	7	V
Peak collector current		I_{CP}	6	A
Collector current		I_C	3	A
Base current		I_B	1.2	A
Collector power dissipation	$T_C = 25°C$	P_C	30	W
	$T_a = 25°C$		2	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

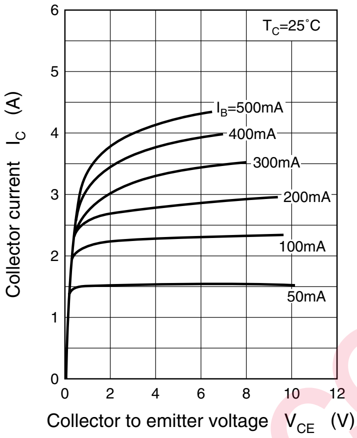
■ Electrical Characteristics $T_C = 25°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = 500 V, I_E = 0			100	µA
Emitter cutoff current	I_{EBO}	V_{EB} = 5 V, I_C = 0			100	µA
Collector to emitter voltage	V_{CEO}	I_C = 10 mA, I_B = 0	400			V
Forward current transfer ratio	h_{FE1}	V_{CE} = 5 V, I_C = 0.1 A	10			
	h_{FE2}	V_{CE} = 2 V, I_C = 1.2 A	8		40	
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = 1.5 A, I_B = 0.3 A			1.0	V
Base to emitter saturation voltage	$V_{BE(sat)}$	I_C = 1.5 A, I_B = 0.3 A			1.5	V
Transition frequency	f_T	V_{CE} = 10 V, I_C = 0.2 A, f = 1 MHz		10		MHz
Turn-on time	t_{on}	I_C = 1.5 A, I_{B1} = 0.15 A, I_{B2} = − 0.3 A, V_{CC} = 200 V			1.0	µs
Storage time	t_{stg}				3.0	µs
Fall time	t_f				0.3	µs

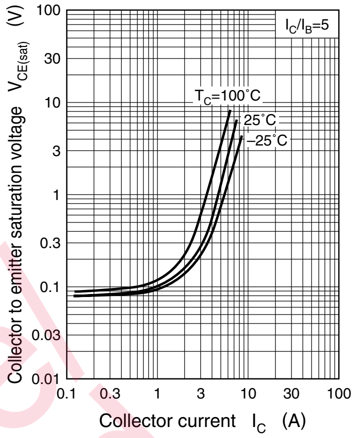
P_C — T_a



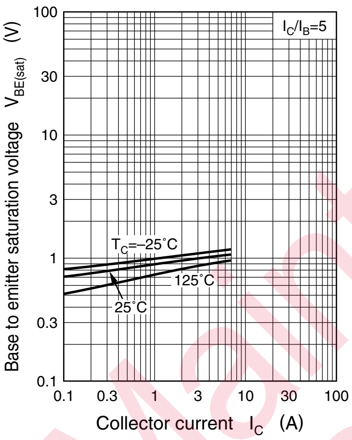
I_C — V_{CE}



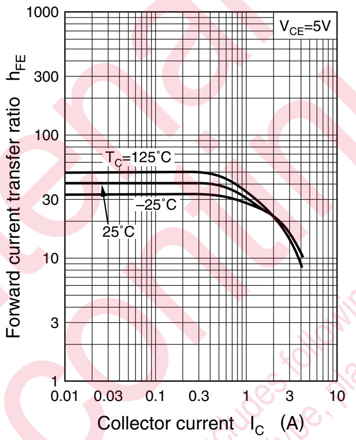
$V_{CE(sat)}$ — I_C



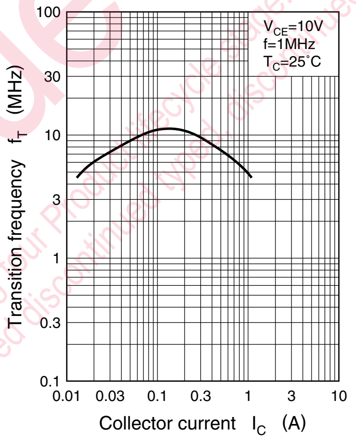
$V_{BE(sat)}$ — I_C



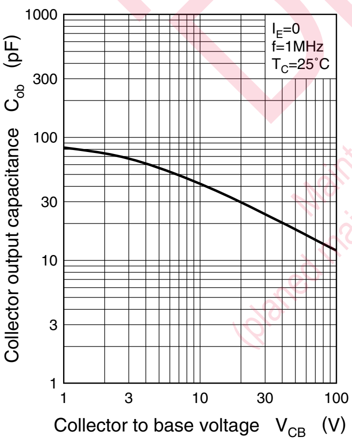
h_{FE} — I_C



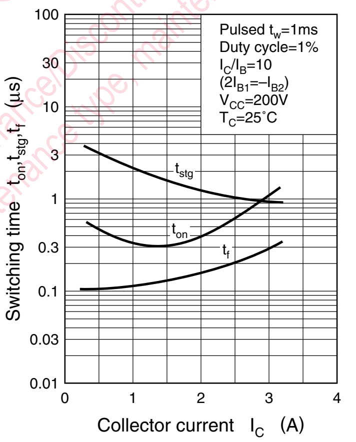
f_T — I_C



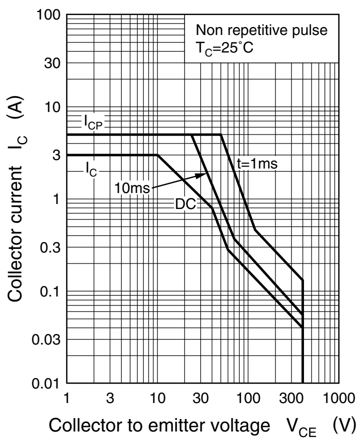
C_{ob} — V_{CB}



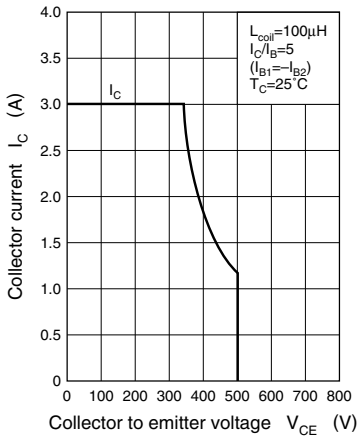
t_{on}, t_{stg}, t_f — I_C



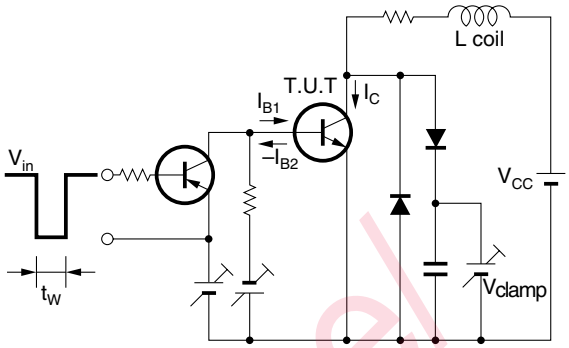
Area of safe operation (ASO)



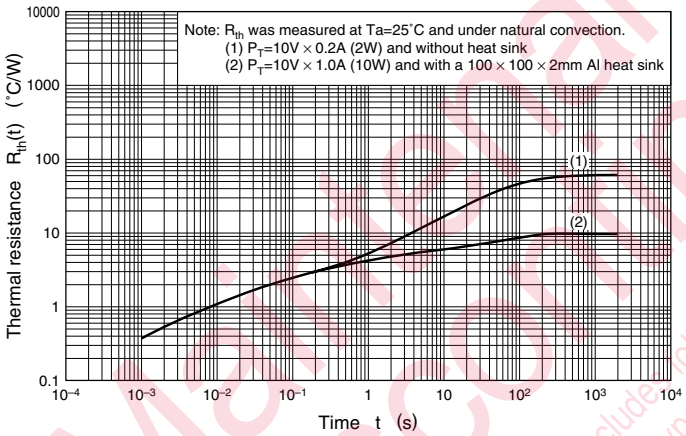
Area of safe operation, reverse bias ASO



Reverse bias ASO measuring circuit



$R_{th(t)}$ — t



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